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### 1. Scope

This product specification contains the test method, the general performance and property for 2.54mm pitch Header Connector series.

#### 2. General items

#### 2.1 Application

This specification applies to the 2.54mm pitch header connector

series 2.2 Operating Temperature Range: -40°C ~ 125°C

2.3 Storage Temperature Range: -40~90 °C

#### 2.4 Test Conditions:

Unless otherwise specified, the tests and measurements are to be carried out in the following standard conditions.

Temperature: 20°C±5°C Relative Humidity: 25%~85%

Air pressure: 86~106 Kpa

### 3. Property

#### 3.1 Materials

| Item    | Standard                                  |
|---------|---|
| Housing | High Temperature Thermoplastic , UL 94V-0 |
| Contact | Copper Alloy                              |

#### 3.2 Ratings

| Item                      | Standard       |
|---------------------------|----------------|
| Current Rating            | 3 A AC/DC      |
| Voltage Rating            | 30V AC         |
| Ambient Temperature Range | -40°C ~ +125°C |
| Storage Temperature Range | -40℃ ~+90℃     |
| Ambient Humidity Range    | 25%~85%        |

| Approved By: | Ady zhou  | Checked By: | Yanghong  | Written By: | Luojiming |
|--------------|-----------|-------------|-----------|-------------|-----------|
| DATE:        | 2015/8/17 | DATE:       | 2015/8/17 | DATE:       | 2015/8/17 |



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### 4. Appearance, construction and dimension:

#### 4.1 Appearance

Each area must be finished well and there must be no rust, scratches, cracks and inferior or peeling plating, etc. that may be harmful in terms of product functioning.

#### 4.2 Construction and dimensions

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

### 5. Test Methods and Requirements:

### **5.1 Electrical Performance**

| Item  | Test Item  | Standard  | Test Condition  |  |  |  |
|---|--|---|---|--|--|--|
| 5.1.1   | 5.1.1 Contact EIA- 364-06C It should be tested in accordance to  |   | 20 mΩ max.(Initial)<br>30 mΩ max.( Final)             |  |  |  |
| 5.1.2   | 5.1.2 Insulation Resistance EIA-364-21C Apply a voltage of DC 500V for 2 minutes between adjacent terminals and measure. |   | 1000 M $\Omega$ min. Initial                          |  |  |  |
| 5.1.3 Withstanding Apply a voltage of AC 500V for 60±5 s to |  | No evidence of<br>Breakdown and flashover nor<br>leakage current exceeds 0.5mA.   |   |  |  |  |
| 5.2 N   | 5.2 Mechanical Performance:  |   |   |  |  |  |
| 5.2.1   | Contact Retention force  | Pull connectors at maximum rate of 25mm/minute  | 700 grams min./per contact                            |  |  |  |
| 5.2.2   | 5.2.2 Insertion force Plug insert into socket shell be an alignment at a constant speed of 25mm/minute.                  |   | 300gf Max per contact.                                |  |  |  |
| 5.2.3   | 5.2.3 Withdrawal force Plug pull out socket shell be an alignment at a constant speed of 25mm/minute                     |   | 20gf Min per contact                                  |  |  |  |
| 5.2.4   | Durability   | EIA-364-09C The sample should be mounted in the tester and fully mated and unmated 50 cycles specified at rate of 25 mm/mini. | See note Contact resistance: 30 m $\Omega$ max. Final |  |  |  |



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| 5.2.5 | Vibration | EIA-364-28D Vibration frequency range:10-55-10Hz/min. Amplitude: 1.52mm Period: 2 hours for each direction X,Y,Z axis. (6 hours total) | See note Contact resistance: $30\ m\Omega$ max. Final No discontinuities of 1 $\mu$ s duration or longer |
|-------|-----------|--|--|
|-------|-----------|--|--|

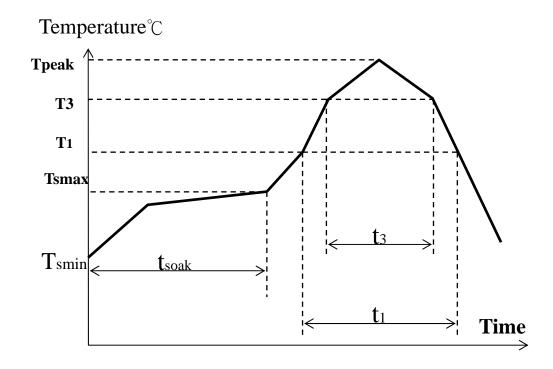
| 5.3 Environmental Performance: |   |   |  |  |  |
|--------------------------------|---|---|--|--|--|
| Humidity                       | EIA-364-31B Temperature: 40 ±2°C Humidity: 90 ~ 95 % (RH) Period: 96 hours(measure should be made within 1hr after, water drops shall be removed)                       | See note Contact resistance: 30 m $\Omega$ max Final Insulation resistance: 100M $\Omega$ min Final   |  |  |  |
| Thermal<br>Shock               | EIA-364-32C<br>One cycle consists of :<br>-40°C for 30 minutes/+125°C for 30<br>minutes.<br>Times of cycle : 5 cycles.  | See note Contact resistance: $30 \text{ m}\Omega$ max Final   |  |  |  |
| Salt Spray                     | EIA-364-26A, Temperature: 35 ±2°C, Density 5% in weight. Period24 ±1 hours(After the test, salt deposit shall be removed in running water)                              | See note Contact resistance: $30 \text{ m}\Omega$ max Final   |  |  |  |
| Temperature Life               | EIA-364-17B<br>Expose a pair of mated connector to 125<br>±2°C for 250 hours  | See Note Contact resistance: 30 m $\Omega$ max Final  |  |  |  |
| thers                          |   |   |  |  |  |
| Solderability                  | EIA-364-52<br>Soldering temperature : 245 ±5°C<br>Immersing time : 4~5sec   | More than 95% of immersed part shall be covered with solder.  |  |  |  |
| Resistance to soldering heat   | EIA-364-56C Soldering iron method: Solder temperature :380±10°C Solder time: 3~5 sec, Reflow : please see recommended profile * The number of reflow is within 2 times. | See Note  |  |  |  |
|                                | Humidity  Thermal Shock  Salt Spray  Temperature Life  thers  Solderability  Resistance to  | Humidity  EIA-364-31B Temperature: 40 ±2°C Humidity: 90 ~ 95 % (RH) Period: 96 hours(measure should be made within 1hr after, water drops shall be removed)  EIA-364-32C One cycle consists of: -40°C for 30 minutes/+125°C for 30 minutes. Times of cycle: 5 cycles.  EIA-364-26A, Temperature: 35 ±2°C, Density 5% in weight. Period24 ±1 hours(After the test, salt deposit shall be removed in running water)  Temperature Life  EIA-364-17B Expose a pair of mated connector to 125 ±2°C for 250 hours  thers  EIA-364-52 Soldering temperature: 245 ±5°C Immersing time: 4~5sec  EIA-364-56C Soldering iron method: Solder temperature: 380±10°C Solder time: 3~5 sec, Reflow: please see recommended profile |  |  |  |



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## 6. Profile for soldering heat resistance testing

| Re-flow soldering profile for heat resistance testing |       |                                       |  |
|---|-------|---------------------------------------|--|
| Parameter   | Mark  | Major parts                           |  |
| Speed of temperature-raising                          |       | Not raise over 3℃ for each second     |  |
| Temperature min Tsmin                                 | Tsmin | 150°C                                 |  |
| Temperature min Tsmax                                 | Tsmax | 200℃                                  |  |
| Time of flux-moistening                               | tsoak | 2~3minutes                            |  |
| Time of temperature over 217°C                        | t 1   | 60~150seconds                         |  |
| Time in the highest temperature range                 | t3    | 5~10 seconds                          |  |
| The highest temperature point                         | Tpeak | 260(+0/-5°C)                          |  |
| Speed of temperature-decreasing                       |       | Not decrease over 6°C for each second |  |
| Time from 25°C to highest temperature                 |       | Not over 8 minutes                    |  |

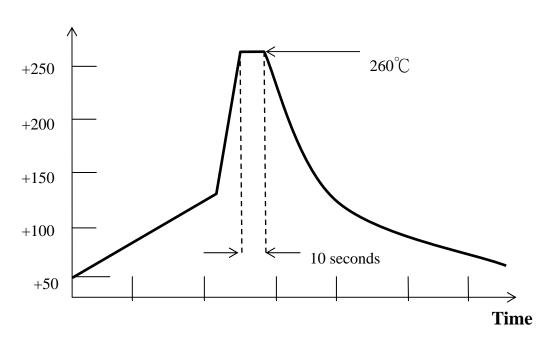


**SMT TYPE Re-flow profile for soldering heat( Lead free)** 



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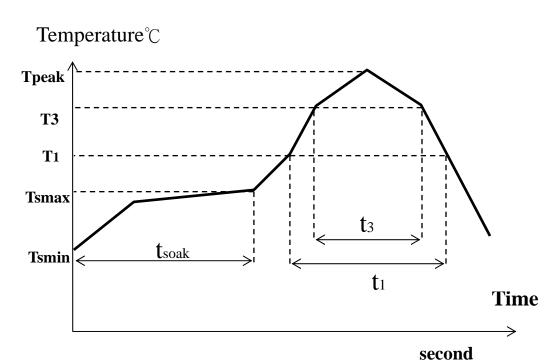
**Dip TYPE** Wave profile for soldering heat (Lead free)

7. The following Profiles are the soldering condition (Reference) temperature for general manufacturing process.

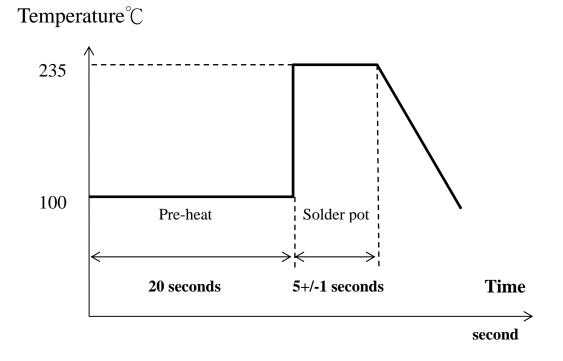
| Example of soldering condition        |        |                                       |  |  |  |  |
|---------------------------------------|--------|---------------------------------------|--|--|--|--|
| Parameter                             | Mark   | Major parts                           |  |  |  |  |
| Speed of temperature-raising          |        | Not raise over 3°C for each second    |  |  |  |  |
| Time of flux-moistening               | t soak | 2~3minutes(150°C~200°C)               |  |  |  |  |
| Time of temperature over 217°C        | t 1    | 60~150seconds                         |  |  |  |  |
| Time in the highest temperature range | t3     | 5~10 seconds                          |  |  |  |  |
| The highest temperature point         | Tpeak  | 235(+0/-5°C)                          |  |  |  |  |
| Speed of temperature-decreasing       |        | Not decrease over 6°C for each second |  |  |  |  |
| Time from 25°C to highest temperature |        | Not over 8 minutes                    |  |  |  |  |



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Reflow profile for soldering heat resistance testing



Wave soldering profile



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8. Product Qualification and Requalification Test Sequence

| . Product Qualifi               | <u>cation</u>     | and R | equalit | ication | Test S | equen | ce  |     |     |  |
|---------------------------------|-------------------|-------|---------|---------|--------|-------|-----|-----|-----|--|
|                                 | Test Group        |       |         |         |        |       |     |     |     |  |
| Test or Examination             | Α                 | В     | С       | D       | Е      | F     | G   | Н   | I   |  |
|                                 | Test Sequence (a) |       |         |         |        |       |     |     |     |  |
| Examination of<br>Product       | 1                 | 1     | 1,5     | 1       | 1,5    | 1,7   | 1,5 | 1,5 | 1,5 |  |
| Contact Resistance              |                   |       | 2,4     |         | 2,4    |       | 2,4 | 2,4 | 2,4 |  |
| Insulation Resistance           |                   |       |         |         |        | 2,6   |     |     |     |  |
| Dielectric Withstanding Voltage |                   |       |         |         |        | 3,5   |     |     |     |  |
| Contact Retention<br>Force      |                   | 2     |         |         |        |       |     |     |     |  |
| Insertion Force                 | 2                 |       |         |         |        |       |     |     |     |  |
| Withdrawal force                | 3                 |       |         |         |        |       |     |     |     |  |
| Vibration                       |                   |       |         |         |        |       |     |     | 3   |  |
| Durability                      |                   |       | 3       |         |        |       |     |     |     |  |
| Solderability                   |                   |       |         | 2       |        |       |     |     |     |  |
| Soldering heat                  |                   |       |         | 3       |        |       |     |     |     |  |
| Humidity                        |                   |       |         |         | 3      |       |     |     |     |  |
| Thermal Shock                   |                   |       |         |         |        | 4     |     |     |     |  |
| Salt Spray                      |                   |       |         |         |        |       | 3   |     |     |  |
| Temperature Life                |                   |       |         |         |        |       |     | 3   |     |  |
| Sample QTY                      | 5                 | 5     | 5       | 5       | 5      | 5     | 5   | 5   | 5   |  |